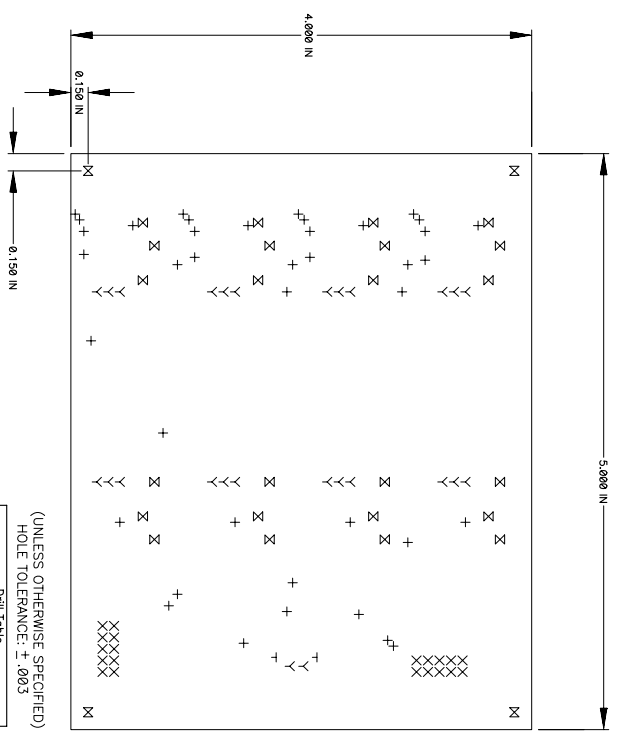


DATE	REV.	BY	CHKD.	DATE	REVISION

1. Fabricate per Engineering Specification
2. Material _____
3. Copper Weight - Finished
Outer Layers _____ OZ.
Inner Layers _____ OZ.
4. Overall Board Thickness _____ +/- _____
5. Finish _____
6. Plated Holes (Barrel) Minimum .001" Thickness
7. Liquid Photo Imageable Soldermask
Sides _____
Color _____
8. Silkscreen
Sides _____
Color _____
9. Build to IPC 600 Class 2

MINIMUM FABRICATION DRAWING INFORMATION

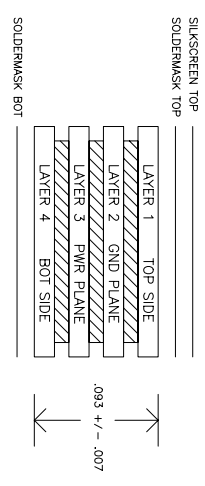
SAMPLE LAYOUT TO INCORPORATE INTO GERBER PACKAGE



(UNLESS OTHERWISE SPECIFIED)
HOLE TOLERANCE: ± .003

Hole Dia (inch)	Symbol	Quantity	Plated
0.012	+	48	Yes
0.035	X	28	Yes
0.040	Y	26	Yes
0.050	Z	2	No
0.051	Z	24	Yes
0.156	M	4	No

STACKUP DETAIL



COMPONENT SIDE

DO NOT SCALE DRAWING

SYMBOLS	PART NO.	NOTICE

PRECISION CIRCUITS		PROJECT NO.	DATE
DESIGNED	DATE	SCALE	
CHECKED	DATE	MATERIAL	
APPROVED	DATE		
RELEASED	DATE		
PART NO.		REV.	

